## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

| Based on | structural | similarity |
|----------|------------|------------|
|----------|------------|------------|

| Supplier                  |                                  | User Part Number   |             |           |            |           |  |
|---------------------------|----------------------------------|--|-------------|-----------|------------|-----------|--|
| Nexperia B.V.             |                                  | PTVS36VP1UTP   |             |           |            |           |  |
| Name of Laboratory        |                                  | Part Description   |             |           |            |           |  |
|                           |                                  | Nexperia DHAM  | Protection  |           |            |           |  |
| Assembly reliability labs |                                  | SMD package  |             |           |            |           |  |
| Based on AEC-Q101 Test    |                                  | Test Conditions  | Duration    | # Lots    | # Quantity | # Rejects |  |
|                           | TEST                             |  |             |           |            |           |  |
|                           | Pre- and Post-Stress             |  |             |           |            |           |  |
| # E1                      | Electrical Test                  | Tamb = 25 °C   | N/A         | see below | all parts  | see below |  |
|                           |                                  | JESD22-A113<br>Bake Tamb = 125 °C  | 24 hours    |           |            |           |  |
|                           | PC                               | Soak Tamb = 85 °C, RH = 85%  | 168 hours   |           |            |           |  |
| # A1                      | Preconditioning                  | Reflow soldering   | 3 cycles    | 286       | 21480      | 0         |  |
|                           | HTRB<br>High Temperature Reverse | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet |             |           |            |           |  |
| # B1                      | Bias                             | reverse voltage  | 1000 hours  | 117       | 9360       | 0         |  |
|                           |                                  |  |             |           |            |           |  |
| # A4                      | TC<br>Temperature Cycling        | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C                        | 1000 cycles | 86        | 6880       | 0         |  |
|                           | , , . <u>.</u>                   | JESD22-A102  | 1000 cycles | 00        | 0000       | 0         |  |
|                           | AC                               | Tamb = $121 ^{\circ}C$ , RH = $100 ^{\circ}M$                              |             |           |            |           |  |
| # A3 alt                  | Autoclave                        | Pressure = $205$ kPa (29.7 psia)   | 96 hours    | 86        | 6880       | 0         |  |
|                           |                                  |  |             |           |            |           |  |
|                           | H3TRB                            | JESD22-A101  |             |           |            |           |  |
|                           | High Humidity High               | Tamb = 85 °C, RH = 85%, VR = 80 % of                                       |             |           |            |           |  |
| # A2 alt                  | Temperature Reverse Bias         | rated reverse voltage <sup>[1]</sup>                                       | 1000 hours  | 86        | 6880       | 0         |  |
|                           |                                  | MIL-STD-750 Method 1037  |             |           |            |           |  |
|                           | IOL                              | ton = toff, devices powered to insure $\Delta Tj$ =                        |             |           |            |           |  |
| # A5                      | Intermittent Operating Life      | 100 °C for 15000 cycles  | 1000 hours  | n.a.      | n.a.       | n.a.      |  |
|                           |                                  |  |             |           |            |           |  |
|                           | RSH<br>Desistance to Colder Uset | JESD22-A111  |             |           |            |           |  |
| # C8                      | Resistance to Solder Heat        | 260 °C ± 5 °C  | 10 s        | 28        | 840        | 0         |  |
|                           | SD<br>Soldorability              | 1 STD 002  |             | 26        | 262        |           |  |
| # C10                     | Solderability                    | J-STD-002  |             | 36        | 360        | 0         |  |

[1]The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab        | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------|----------|---------|--------------------|------------|
| Nexperia<br>DHAM | Protection | 9360     | 0       | 0.45               | 2.20E+09   |

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